



Partial Equipment Listing

	<b>SMT Line 1: High speed production</b>	<b>SMT Line 2: High speed production</b>	<b>SMT Line 3: Prototype/low volume</b>	<b>SMT Line 4: Prototype/low volume</b>
<b>Stencil Printer</b>	DEK Horizon fully automated w/vision	DEK Horizon fully automated w/vision	MPM semi automated w/ vision	MPM semi automated w/ vision
<b>Chip Placer</b>	FUJI CP7	FUJI CP4	Mydata TP11 w/Hydra Option	Mydata MY9 w/Hydra Option
<b>IC Placer</b>	FUJI XP2	FUJI IP2	Same machine	Same machine
<b>Parts Per Hour</b>	Chips: 53,000, IC's:	Chips: 25,000, IC's:	Mixed up to 16,000	Mixed up to 21,000
<b>Component Packages</b>	0201 thru 45mm x 150mm BGA	0402 thru 54mm sq. BGA	0402 thru large scale BGA	0201 thru large scale BGA
<b>Finest Placement Pitch</b>	0.30mm	0.30mm	0.38mm	0.25mm
<b>Max Board size</b>	14" x 18"	14" x 18"	15" x 20"	15" x 20"
<b>Component Packages</b>	0201 thru 45mm x 150mm BGA	0402 thru 54mm sq. BGA	0402 thru large scale BGA	0201 thru large scale BGA
<b>Reflow Ovens</b>	(2) Heller 1500SX 5 Zone, (1) Heller 1809EXL 10 Zone, 100% Forced Air Convection, profiles optimized to support all lines.			

**Production Support Equipment**

- AirVac DRS24C BGA Rework Station: Automated removal, placement & reflow of BGA, CSP, Flip Chip, leaded devices & connectors
- Edsyn ZD906 Multi-Tasking Rework Station
- Electrovert EconoPak Plus, Dual wave solder machine
- Eubanks 2700 Wire-Stripper
- General Signal 'BLUE' Baking Chamber for moisture sensitive devices
- Dry-Pack Sealer for moisture sensitive devices
- Westkleen Triton Cleaning System with De-Ionized Water
- HEPCO universal BGA reballer

- VJ Technologies VJ1000: X-Ray for BGAs, 120Kv real time x-ray with analytical software to detect voids
- CR Technology 6520 Automated Optical Inspection Machine
- Ersascope: Optical inspection equipment allowing visual inspection of BGA and other hidden solder joints under the component
- Takaya APT8400: fixtureless, 4 head, flying probe tester- up to 100% testability for solder joints and passive values

**Test and Inspection**